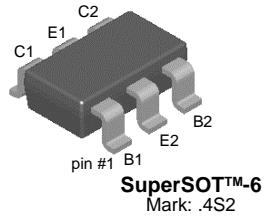


# FMBM5401

## PNP General Purpose Amplifier

- This device has matched dies in SuperSOT-6.



### Absolute Maximum Ratings\*

Symbol	Parameter	Value	Units
$V_{CEO}$	Collector-Emitter Voltage	-150	V
$V_{CBO}$	Collector-Base Voltage	-160	V
$V_{EBO}$	Emitter-Base Voltage	-5.0	V
$I_C$	Collector Current - Continuous	-600	mA
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 ~ 150	°C

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

**Notes:**

- These ratings are based on a maximum junction temperature of 150 degrees C.
- These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Max	Units
<b>Off Characteristics</b>					
$BV_{CEO}$	Collector-Emitter Breakdown Voltage *	$I_C = -1.0\text{mA}, I_B = 0$	-150		V
$BV_{CBO}$	Collector-Base Breakdown Voltage	$I_C = -100\mu\text{A}, I_E = 0$	-160		V
$BV_{EBO}$	Emitter-Base Breakdown Voltage	$I_C = -10\mu\text{A}, I_C = 0$	-5.0		V
$I_{CBO}$	Collector Cut-off Current	$V_{CB} = -120\text{V}, I_E = 0$ $V_{CB} = -120\text{V}, I_E = 0, T_a = 100^\circ\text{C}$		-50 -50	nA $\mu\text{A}$
$I_{EBO}$	Emitter Cut-off Current	$V_{EB} = -3.0\text{V}, I_C = 0$		-50	nA
<b>On Characteristics*</b>					
$h_{FE1}$	DC Current Gain	$V_{CE} = -5\text{V}, I_C = -1\text{mA}$	50		
DIVID1	Variation Ratio of $h_{FE1}$ Between Die 1 and Die 2	$h_{FE1}(\text{Die1})/h_{FE1}(\text{Die2})$	0.9	1.1	
$h_{FE2}$	DC Current Gain	$V_{CE} = -5\text{V}, I_C = -10\text{mA}$	60	240	
DIVID2	Variation Ratio of $h_{FE2}$ Between Die 1 and Die 2	$h_{FE2}(\text{Die1})/h_{FE2}(\text{Die2})$	0.95	1.05	
$h_{FE3}$	DC Current Gain	$V_{CE} = -5\text{V}, I_C = -50\text{mA}$	50		
DIVID3	Variation Ratio of $h_{FE3}$ Between Die 1 and Die 2	$h_{FE3}(\text{Die1})/h_{FE3}(\text{Die2})$	0.9	1.1	

**Electrical Characteristics** (Continued)  $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Conditions	Min.	Max	Units
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = -10\text{mA}, I_B = -1\text{mA}$ $I_C = -50\text{mA}, I_B = -5\text{mA}$	-0.2 -0.5	V V	
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C = -10\text{mA}, I_B = -1\text{mA}$ $I_C = -50\text{mA}, I_B = -5\text{mA}$		-1 -1	V V
$V_{BE(on)}$	Base-Emitter On Voltage	$V_{CE} = -5\text{V}, I_C = -10\text{mA}$		-1	V
DEL	Difference of $V_{BE(on)}$ Between Die1 and Die 2	$V_{BE(on)}(\text{Die1}) - V_{BE(on)}(\text{Die2})$	-8	8	mV
<b>Small Signal Characteristics</b>					
$f_T$	Current Gain Bandwidth Product	$V_{CE} = -10\text{V}, I_C = -10\text{mA}$ $f = 100\text{MHz}$	100	300	MHz
$C_{ob}$	Output Capacitance	$V_{CB} = -10\text{V}, I_E = 0, f = 1\text{MHz}$		6.0	pF
NF	Noise Figure	$V_{CE} = -5.0\text{V}, I_C = -250\mu\text{A},$ $R_S = 1.0\text{K}\Omega, f = 10\text{Hz to } 15.7\text{KHz}$		8.0	dB

\* Pulse Test: Pulse Width  $\leq 300\text{ms}$ , Duty Cycle  $\leq 2.0\%$

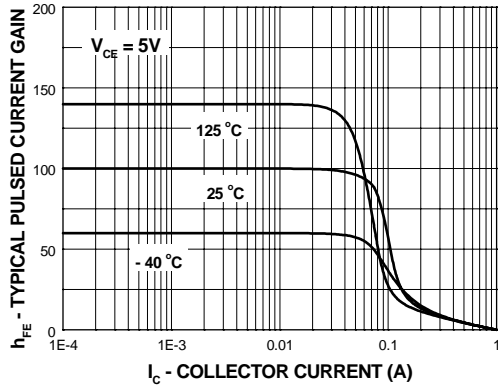
**Thermal Characteristics**  $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Value	Units
$P_D$	Total Device Dissipation	700	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Total	180	$^\circ\text{C/W}$

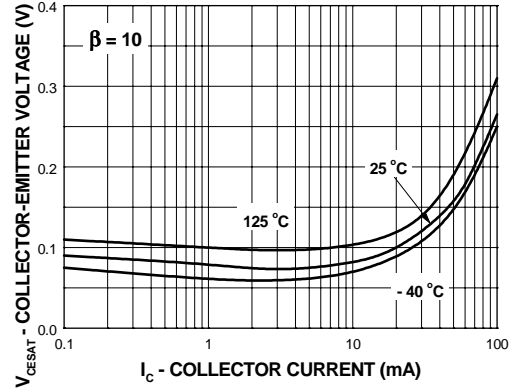
\* Device mounted on a 1 in 2 pad of 2 oz copper

## Typical Performance Characteristics

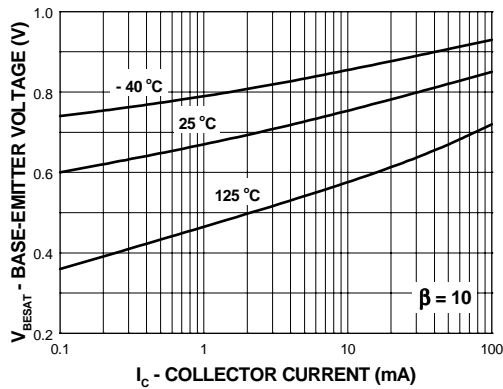
**Figure 1. Typical Pulsed Current Gain vs Collector Current**



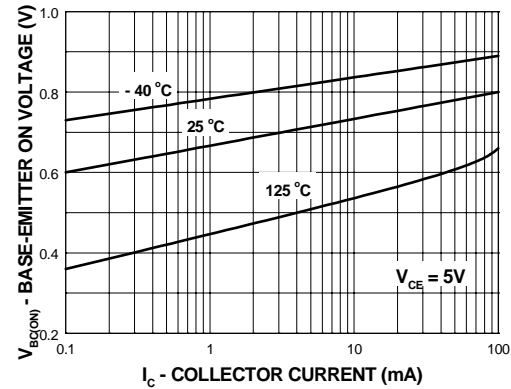
**Figure 2. Collector-Emitter Saturation Voltage vs Collector Current**



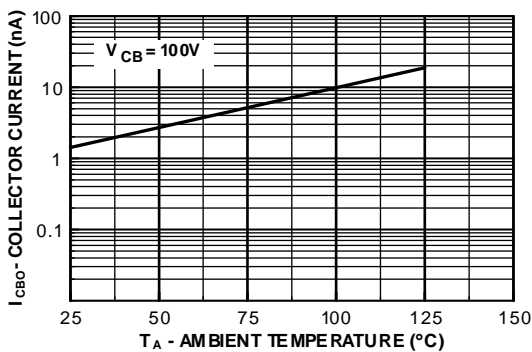
**Figure 3. Base-Emitter Saturation Voltage vs Collector Current**



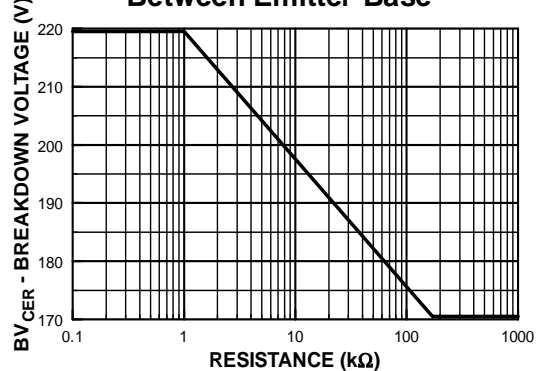
**Figure 4. Base-Emitter On Voltage vs Collector Current**



**Figure 5. Collector-Cutoff Current vs Ambient Temperature**

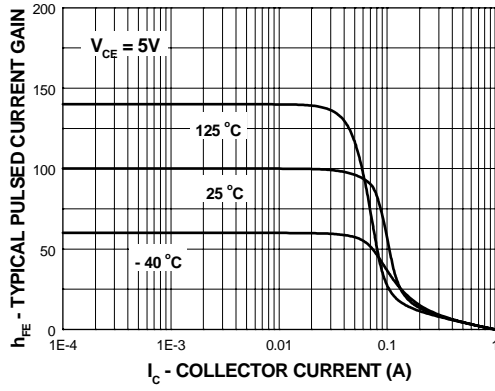


**Figure 6. Collector-Emitter Breakdown Voltage with Resistance Between Emitter-Base**



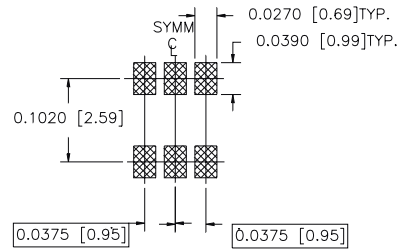
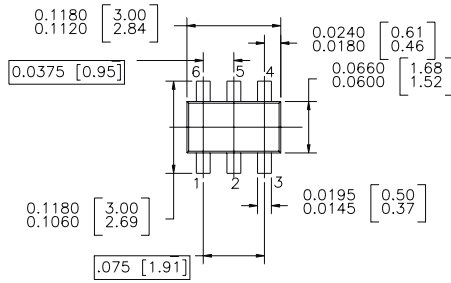
Typical Performance Characteristics (Continued)

Figure 7. Input and Output Capacitance vs Reverse Voltage



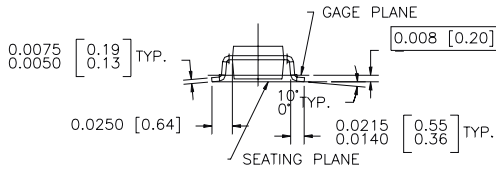
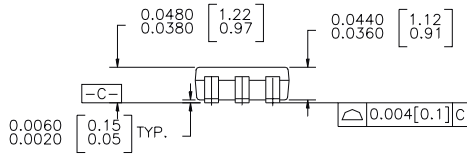
## Mechanical Dimensions

# SuperSOT™-6



LAND PATTERN RECOMMENDATION

CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS



SUPER SOT 6 LEADS

NOTES : UNLESS OTHERWISE SPECIFIED

1.0 STANDARD LEAD FINISH : 150 MICRONS / 93.81 MICROMETERS)  
MINIMUM TIN / LEAD (SOLDER) ON COPPER.

2.0 NO JEDEC REGISTRATION AS OF JULY 1996

Dimensions in Millimeters

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CoolFET™	FRFET™	MICROCOUPLER™	PowerSaver™	SuperSOT™-3
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EcoSPARK™	HiSeC™	MICROWIRE™	QS™	SyncFET™
E <sup>2</sup> CMOST™	I <sup>2</sup> C™	MSX™	QT Optoelectronics™	TinyLogic <sup>®</sup>
EnSigna™	<i>i-Lo</i> ™	MSXPro™	Quiet Series™	TINYOPTO™
FACT™	ImpliedDisconnect™	OCX™	RapidConfigure™	TruTranslation™
FACT Quiet Series™		OCXPro™	RapidConnect™	UHC™
Across the board. Around the world.™		OPTOLOGIC <sup>®</sup>	$\mu$ SerDes™	UltraFET <sup>®</sup>
The Power Franchise <sup>®</sup>		OPTOPLANAR™	SILENT SWITCHER <sup>®</sup>	UniFET™
Programmable Active Droop™		PACMAN™	SMART START™	VCX™

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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